



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Michael S. Leung, et al.

Serial No. 10/666,399

Filed: September 18, 2003

Examiner: Le, Thao X

Art Unit: 2814

Conf. No. 8955

Cust. No. 23935

Docket No. P0298US-7

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action mailed on July 19, 2007, please consider the remarks and arguments presented below and amend the above-identified application as follows:

AMENDMENTS TO THE CLAIMS are shown beginning on page 2 of this paper.

REMARKS AND ARGUMENTS begin on page 11 of this paper.